



## Materials Declaration Form

<b>IPC Form Type *</b>	1752 Distribute	<b>Version</b>	2
<b>Sectionals *</b>	Material Info Manufacturing Info	<b>Subsectionals *</b>	A-D
<i>* : Required Field</i>			

Supplier Information			
<b>Company Name *</b>	STMicroelectronics	<b>Response Date *</b>	2016-11-22
<b>Contact Name *</b>	Refer to "Supplier Comment" section	<b>Contact Title</b>	Refer to "Supplier Comment" section
<b>Contact Phone *</b>	Refer to "Supplier Comment" section	<b>Contact Email *</b>	Refer to "Supplier Comment" section
<b>Authorized Representative *</b>	Rossana Bonaccorso	<b>Representative Title</b>	ADG MD CHAMPION
<b>Representative Phone *</b>	Refer to "Supplier Comment" section	<b>Representative Email *</b>	Refer to "Supplier Comment" section
<b>Supplier Comment</b>	Online Technical Support - STMicroelectronics : <a href="http://www.st.com/web/en/support/support.html">http://www.st.com/web/en/support/support.html</a>		

**Uncertainty Statement**


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Legal Statement			
<b>Supplier Acceptance *</b>	true	<b>Legal Declaration *</b>	Standard

**Legal Statement**

Supplier certifies that it gathered the provided information and such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form.

Product				
Mfr Item Number	Mfr Item Name	Version	Mfr Site	Date
L93PI	B5Z7*U538CA6	A	MU1A	2016-11-22
Amount		UoM	Unit type	ST ECOPACK Grade
532.29		mg	Each	ECOPACK® 1

Manufacturing information				
J-STD-020 MSL Rating	Classification Temp	Nbr of Reflow Cycles	 life.augmented	
3	250	3		
bulk Solder Termination	Terminal Plating	Terminal Base Alloy	Comment	
NAC	Sold (Ni/Pd/Au), ENEPIG Tin/Bismu	Copper Alloy		

Package Designator	Size	Nbr of instances	Shape	
CHP	12.8x7.5x2.3	20	flat	
Comment				

QueryList : RoHS Directive 2011/65/EU-July 2011 – Annex II amended by Directive 2015/863-April 2015	
Query	Response
Product(s) meets EU RoHS requirement without any exemptions	<b>true</b>
Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7b' exemption (other selected exemptions may apply)	false
Product(s) meets EU RoHS requirements by application of the selected exemption(s)	false
Product(s) does not meet EU RoHS requirements and is not under exemptions	false
Product(s) is obsolete, no information is available	false
Product(s) is unknown, no information is available	false
Exemption Id.	Description

QueryList : REACH-20th June 2016				
Query				Response
The product does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH				<b>true</b>
CategoryLevel_Name	CategoryLevel_Threshold	amount in product (mg)	Application	ppm in product

Material Composition Declaration						Mfr Item Name	BSZ7*U538CA6					
Homogeneous Material	Material Group	Mass	UoM	Level	Substance Category	Substance	CAS	Exempt	Mass	UoM	Concentration in homogeneous material (ppm)	Concentration in product (ppm)
Die	Other inorganic materials	5.386	mg	supplier	die	Silicon (Si)	7440-21-3		5.239	mg	972707	9842
				supplier	metallization	Aluminium (Al)	7429-90-5		0.030	mg	5570	56
				supplier	metallization	Copper (Cu)	7440-50-8		0.030	mg	5570	56
				supplier	passivation	Silicon Oxide(SiO2)	7631-86-9		0.017	mg	3156	32
				supplier	passivation	Indium Tin oxide ( In2O3:SnO2 )	50926-11-9		0.070	mg	12997	132
Leadframe	Copper & its alloys	151.276	mg	supplier	alloy	Copper (Cu)	7440-50-8		146.569	mg	968885	275356
				supplier	alloy	Iron (Fe)	7439-89-6		3.447	mg	22786	6476
				supplier	alloy	Iron Phosphide (FeP)	26508-33-8		0.208	mg	1375	391
				supplier	alloy	Zinc (Zn)	7440-66-6		0.180	mg	1190	338
				supplier	metallization	Nickel (Ni)	7440-02-0		0.800	mg	5288	1503
				supplier	metallization	Palladium (Pd)	7440-05-3		0.051	mg	337	96
				supplier	metallization	Gold (Au)	7440-57-5		0.021	mg	139	39
Die attach	Other Organic Materials	1.291	mg	supplier	glue or tape	Silver (Ag)	7440-22-4		0.994	mg	769946	1867
				supplier	glue or tape	Epoxy Cresol Novolak	29690-82-2		0.294	mg	227730	552
				supplier	glue or tape	1-isopropyl-2,2-dimethyltrimethylene diisobut	6846-50-0		0.003	mg	2324	6
Bonding wire	Precious metals	0.866	mg	supplier	wire	Gold (Au)	7440-57-5		0.866	mg	1000000	1626
Encapsulation	Other Organic Materials	373.472	mg	supplier	mold compound	Silica, vitreous	60676-86-0		298.777	mg	799998	561305
				supplier	mold compound	Epoxy Cresol Novolak	29690-82-2		26.143	mg	70000	49114
				supplier	mold compound	Phenol resin	9003-35-4		14.939	mg	40000	28066
				supplier	mold compound	Biphenyl epoxy resin	85954-11-6		22.409	mg	60002	42099
				supplier	mold compound	Antimony Trioxide	1309-64-4		4.482	mg	12001	8420
				supplier	mold compound	Brominated Epoxy Resin	40039-93-8		5.602	mg	15000	10524
				supplier	mold compound	Carbon Black	1333-86-4		1.120	mg	2999	2104